

KPKF-3030QWXXC-C

WHITE

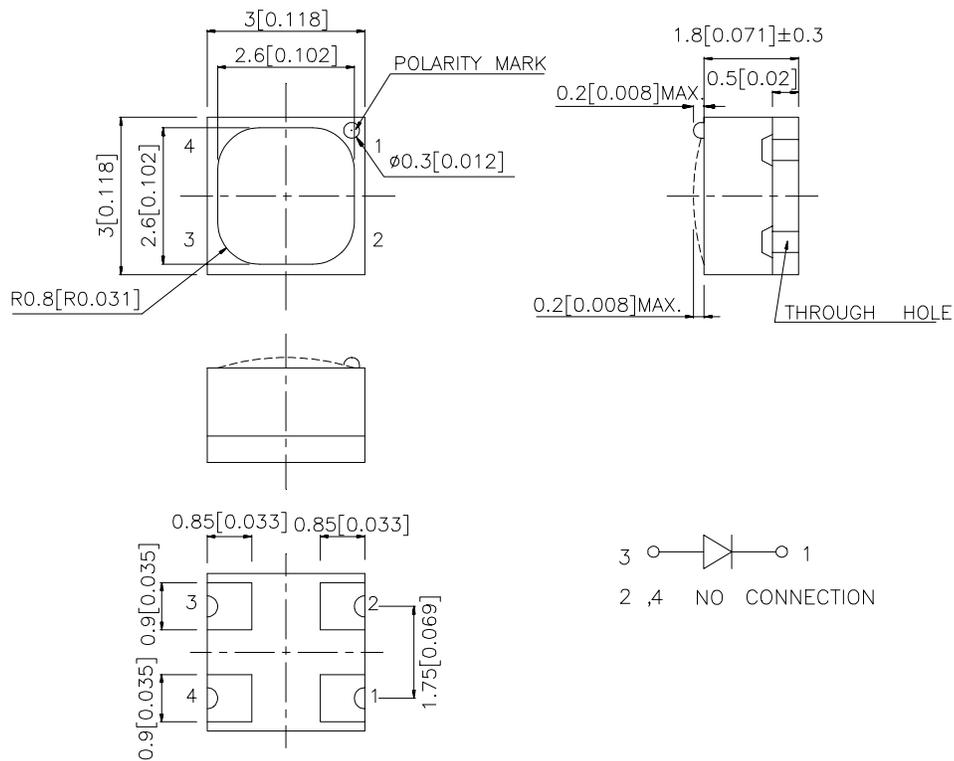
### Features

- LOW POWER CONSUMPTION.
- 3.0mmx3.0mm SMT LED, 2.0mm(MAX.) THICKNESS.
- ONE WHITE CHIP IN ONE PACKAGE.
- CAN PRODUCE ANY COLOR IN VISIBLE SPECTRUM, INCLUDING WHITE LIGHT.
- PACKAGE : 1000PCS / REEL.

### Description

The source color devices are made with GaN on Sapphire Light Emitting Diode.

### Package Dimensions



### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.2$  (0.008") unless otherwise noted.
3. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
KPKF-3030QWXC-C	WHITE( GaN )	WATER CLEAR	70	280	100°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
V <sub>F</sub>	Forward Voltage	White	3.3	4.0	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	White		10	μA	V <sub>R</sub> =5V
X	Chromaticity Coordinates	White	0.33			
Y			0.34			
C	Capacitance	White	105		pF	V <sub>F</sub> =0V, f=1MHz

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

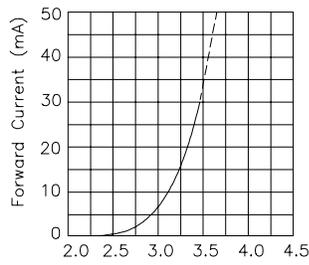
Parameter	White	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

Note:

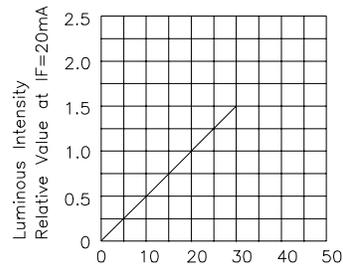
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

White

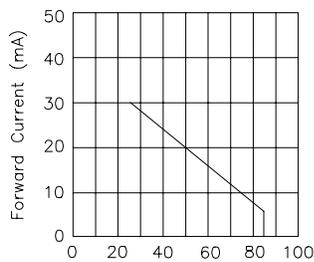
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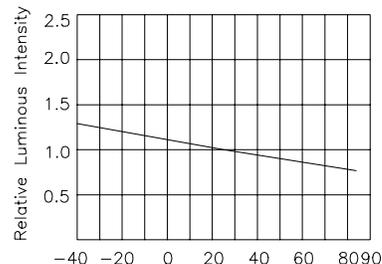
Forward Voltage(V)  
FORWARD CURRENT Vs.  
FORWARD VOLTAGE



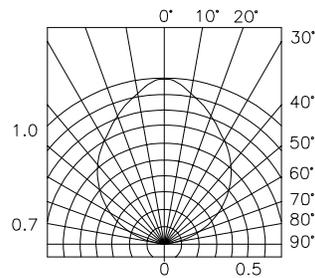
$I_F$ —Forward Current (mA)  
LUMINOUS INTENSITY Vs.  
FORWARD CURRENT



Ambient Temperature  $T_A$  (°C)  
FORWARD CURRENT  
DERATING CURVE



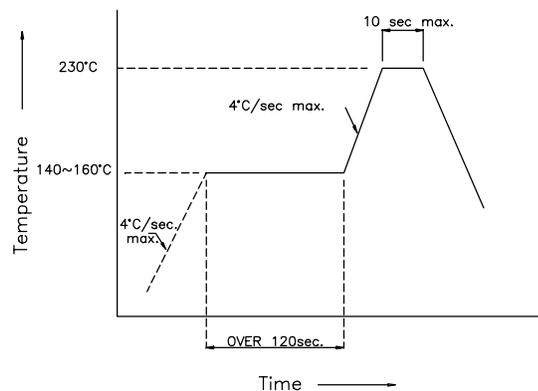
Ambient Temperature  $T_A$  (°C)  
LUMINOUS INTENSITY Vs.  
AMBIENT TEMPERATURE



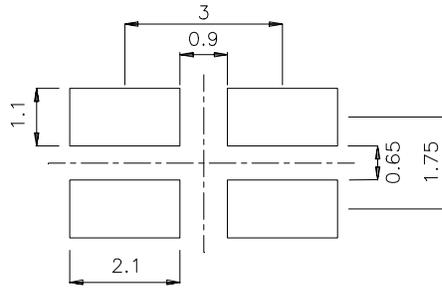
SPATIAL DISTRIBUTION

## KPKF-3030QWXXC-C SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



## Recommended Soldering Pattern (Units : mm)



## Tape Specifications (Units : mm)

